

Rev.I.Feb.-2019

SOD-123

Schottky Diode in a SOD-123 Plastic Package.

Low positive pressure drop. HF Product.

Schottky diode.



PIN1:Cathode

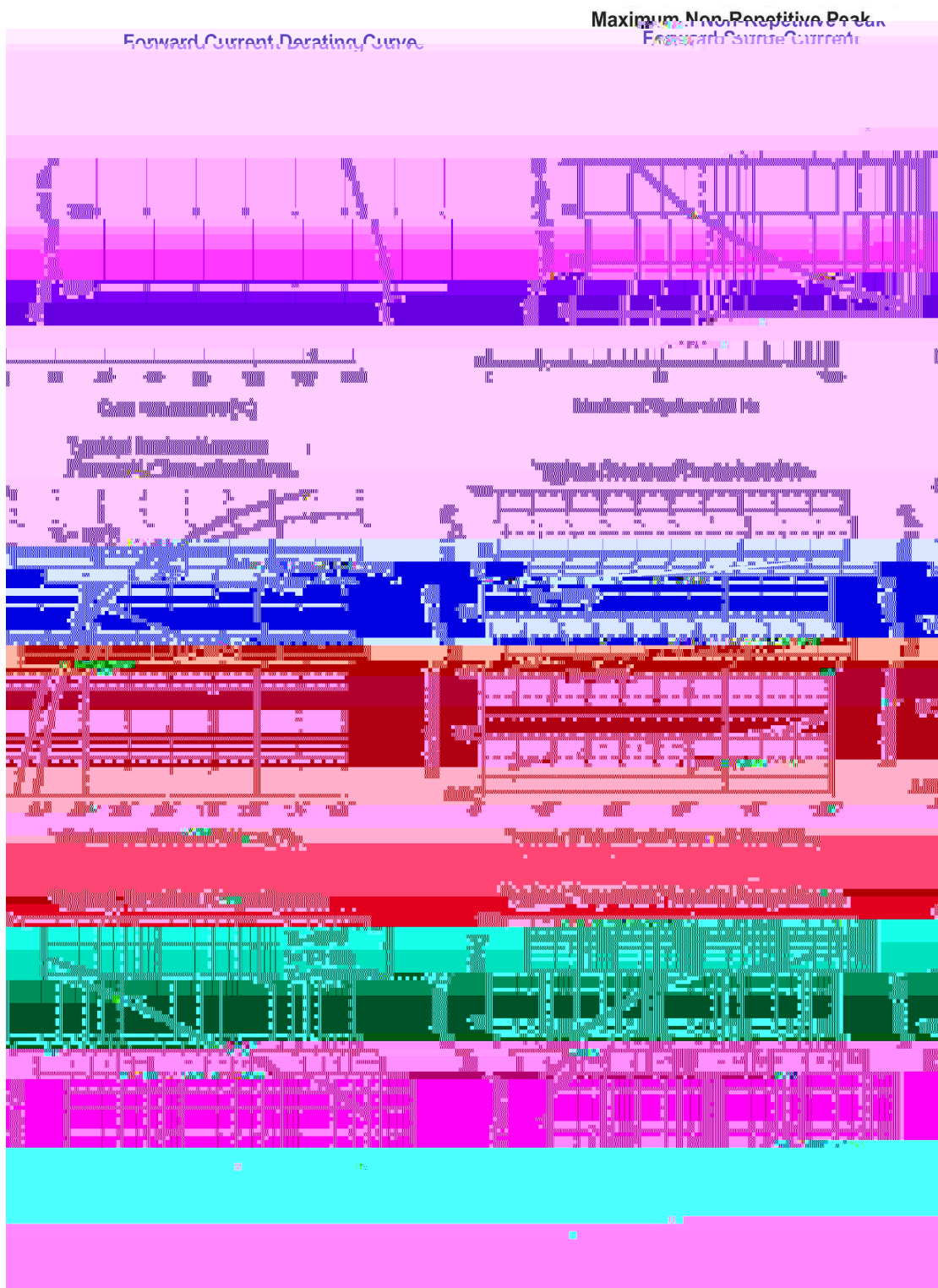
PIN2:Anode

Model	B5817W	B5818W	B5819W
Marking	HSJ	HSK	HSL

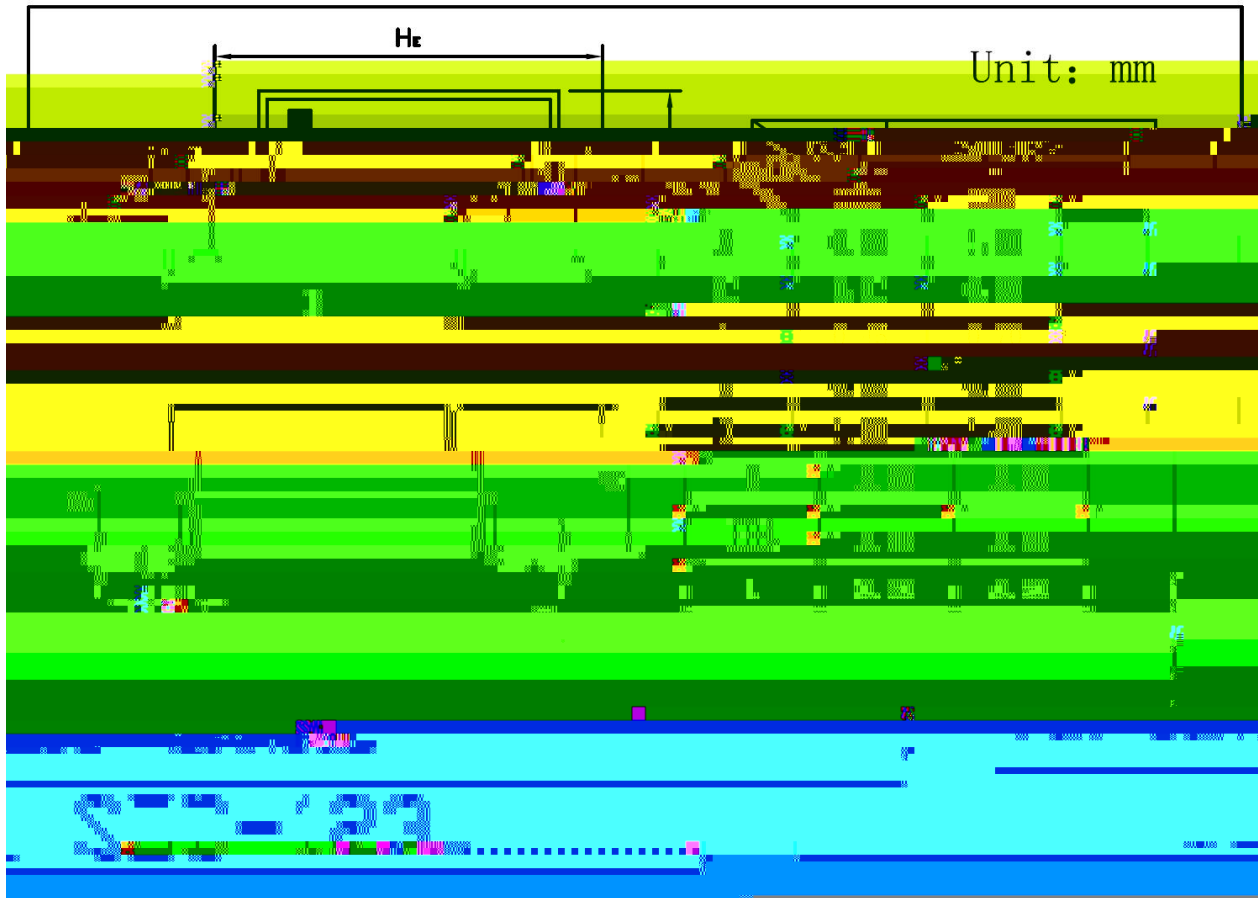
Parameter	Symbol	Rating			Unit
		B5817W	B5818W	B5819W	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Reverse Voltage	V_{RRM} V_{RWM} V_R	20	30	40	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	V
Average Rectified Forward Current	I_F	1			A
Non-Repetitive Peak Forward Surge Current	I_{FSM}	25			A
Power Dissipation	P_D	450			mW
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	220			°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	-65 to 125			°C

Parameter	Symbol	Test Conditions	Rating						Unit
			B5817W		B5818W		B5819W		
			MIN	MAX	MIN	MAX	MIN	MAX	
Reverse breakdown voltage	V _(BR)	I _R =1mA	20		30		40		V
Forward Voltage	V _F	I _F =0.1A		0.32		0.35		0.40	V
		I _F =1A		0.45		0.55		0.60	
		I _F =3A (t<5us)		0.75		0.875		0.90	
Instantaneous Reverse Current	I _{RM}	V _R =V _{RRM}	1						mA
Junction Capacitance	C _J	V _R =4V f=1.0MHZ	120						pF

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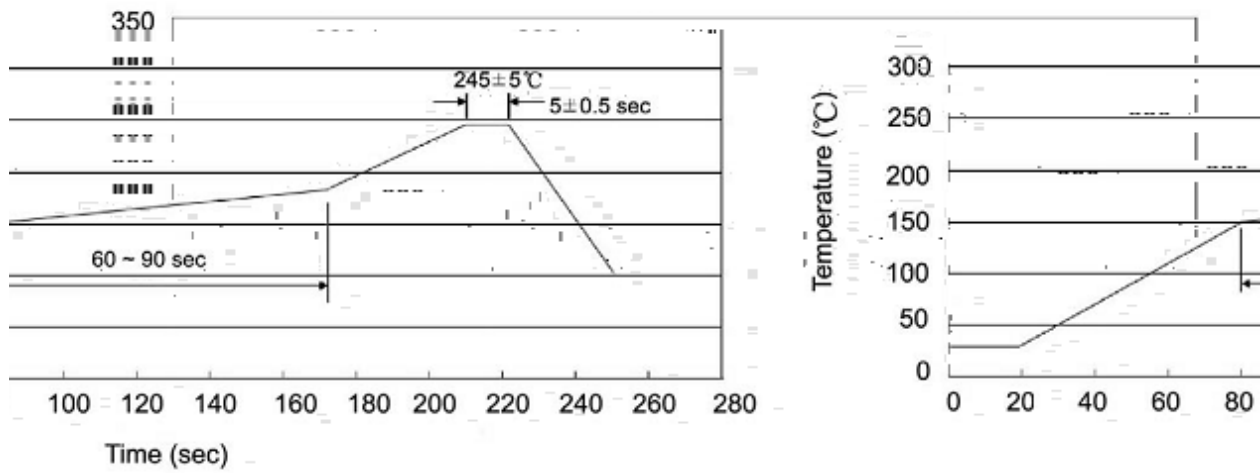


Note:

H: Company Code.

SJ: Product Type.

Temperature Profile for IR Reflow Soldering(Pb-Free)



- Note:
- 1.Preheating:150~180 , Time:60~90sec.
 - 2.Peak Temp.:245 5 , Duration:5 0.5sec.
 - 3. Cooling Speed: 2~10 /sec.

260 5 10 1 sec. Temp.:260 5 Time:10 1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
						"		